FOR IMMEDIATE RELEASE

Diodes, Inc. Launches New PowerDI™5 Compact Power Package with the Release of High Voltage Schottky Barrier Rectifiers

- New line using patent-pending PowerDI™5 package delivers high amperage performance with increased miniaturization and efficiency

Westlake Village, California – October 19, 2004 – Diodes Incorporated, (Nasdaq: DIOD) a leading manufacturer and supplier of high quality discrete semiconductors, today announced the release of the new high voltage PDS3200 and PDS5100H Schottky Barrier Rectifiers in a new high-current density package type, PowerDI™5, developed and manufactured solely by Diodes Incorporated.

Building upon the momentum generated by Diodes’ performance packaging platforms including PowerDI™123 and Powermite®3, the new patent-pending PowerDI™5 is able to accommodate larger die sizes and higher amperage so as to broaden the range of high performance next generation discrete devices that Diodes, Inc. is able to offer to its customers. Similar to Diodes’ patented PowerDI™123 package, the new PowerDI™5 package uses a flat lead frame heat-sink solder pad to achieve thermal performance unequaled by legacy SMC and DPAK package designs. The improvements in space and power consumption, combined with high amperage capabilities, make the new package ideally suited for a wide range of demanding end-equipment applications, including the automotive, computing and telecommunications markets.

The first products in the PowerDI™5 family to be released in short succession are the high-efficiency 3 Ampere, 200 Volt low leakage Schottky Barrier rectifier device PDS3200, and the 5 Ampere, 100 volt low leakage PDS5100H. Both devices offer standout ultra-low leakage current performance and are more stable under high-stress operation than the traditional SMC. The devices are the first product releases to incorporate Diodes’ patented ultra-low leakage, high voltage Schottky barrier rectifier process. This breakthrough process, which was announced in 2003, makes it possible to achieve 70% lower leakage than legacy chips with equivalent or lower $V_F$, with lower heat generation and smaller die size.

“We are excited about the introduction of this first Schottky rectifier series in our industry-leading PowerDI™5 packaging technology,” said Diodes’ President and CEO, C.H. Chen. “This further exemplifies Diodes’ commitment to becoming an innovation leader for discrete devices. We are dedicated to the ongoing development of core intellectual properties that enable us to transcend the current limits of performance, size and power consumption.”

“The PowerDI™5 series represents another important element in Diodes’ expanding product range, offering space-savings advantages for high-amperage applications that respond to customer needs across many of our core end-equipment categories,” said Mark King, Vice President of Sales and Marketing. “Preliminary customer interest in our PowerDI™5 has been very intense, especially from the automotive end-equipment market. We expect to roll out a series of PowerDI™5 products in the upcoming months.”
Ideal for applications requiring high current density in sub-miniature footprints and/or a very low profile device, the PowerDI™5 has a printed circuit board (PCB) footprint of only 1.1mm in height and only 26mm² in area, with over 45% PCB space savings as compared with 47mm² for SMC and 61.5mm² for DPAK, as well as lower forward voltage drop and higher surge current capabilities for optimum power efficiencies. These advantages are critical to manufacturers that require increased functionality in smaller packages, such as the catch diode for buck regulators, reverse polarity protection, battery charging, switching power supplies, freewheeling diodes, and other portable applications.

Responding to an increase in inquiries and requests from environmentally conscious markets such as Europe and Japan, Diodes’ products are manufactured using an environmentally friendly molding compound as well as lead-free terminal plating.

The initial PowerDI™5 product release includes a series of highly efficient Schottky Barrier Rectifier components that range from 5 to 12 Ampere for current rating and from 20 Volts to 200 Volts for reverse breakdown. With PDS3200 and PDS5100H being first to market, Diodes, Inc. is planning a release of multiple new PowerDI™5 products, including ultrafast recovery rectifiers, transient voltage suppressors (TVSs), standards recovery rectifiers, MOSFETS, and Bipolar transistors, in the coming months.

Schottky Barrier parts are in stock and available for delivery. Please check our website at www.diodes.com for a complete PowerDI™5 product list.

All Schottky Barrier rectifier wafers used in the PowerDI™5 series are made at Diodes’ wafer foundry, FabTech, Inc. located in the USA, and the products are assembled in Diodes, Inc.’s manufacturing facilities in China.

For more information, visit http://www.diodes.com or contact Diodes’ customer service at 800-446-4800 or email at info@diodes.com.

PowerDI is a trademark of Diodes Incorporated.
POWERMITE is a registered trademark of Microsemi Corporation.

About Diodes Incorporated
Diodes Incorporated (Nasdaq: DIOD) is a leading manufacturer and supplier of high-quality discrete semiconductor products, serving the communications, computer, industrial, consumer electronics and automotive markets. The Company operates three Far East subsidiaries, Diodes-China (QS-9000 and ISO-14001 certified) in Shanghai, Diodes-Taiwan (ISO-9000 certified) in Taipei, and Diodes-Hong Kong. Diodes-China’s manufacturing focus is on subminiature surface-mount devices destined for wireless devices, notebook, flat panel display, digital camera, mobile handset, set top box, DC to DC conversion, and automotive applications, among others. Diodes-Taiwan is our Asia-Pacific sales, logistics and distribution center. Diodes-Hong Kong covers sales warehouse and logistics functions. The Company’s 5” wafer foundry, Diodes-FabTech (QS-9000 certified), specializes in Schottky products and is located just outside Kansas City, Missouri. The Company’s ISO-9000 corporate sales, marketing, engineering and logistics headquarters is located in Southern California. For further information, visit the Company’s website at http://www.diodes.com.

Safe Harbor Statement Under the Private Securities Litigation Reform Act of 1995: Any statements set forth above that are not historical facts are forward-looking statements that involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. Potential risks and uncertainties include, but are not limited to, such factors as fluctuations in product demand, the introduction of new products, the Company’s ability to maintain customer and
vendor relationships, technological advancements, impact of competitive products and pricing, growth in targeted markets, risks of foreign operations, and other information detailed from time to time in the Company's filings with the United States Securities and Exchange Commission.

Source: Diodes Incorporated
CONTACT: Crocker Coulson, President, Coffin Communications Group, (818) 789-0100, e-mail: crocker.coulson@ccgir.com or Mark King, Vice President Sales & Marketing, Diodes, Inc., (805) 446-4800.

Recent news releases, annual reports, and SEC filings are available at the Company’s website: http://www.diodes.com. Written requests may be sent directly to the Company, or they may be e-mailed to: diodes-fin@diodes.com.

###